### **General Description**

The SJ80N065 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 10V. This device is suitable for use as a wide variety of applications.

#### **Features**

- Low Gate Charge
- 100% UIS Tested, 100% DVDS Tested
- High Power and current handing capability
- Lead free product is acquired

### **Application**

- PWM Applications
- Load Switch
- Power Management

### **Key Performance Parametes**

Parameter	Value	Unit
V <sub>DS</sub>	80	V
R <sub>DS(ON)_TYP</sub>	6.8	mΩ
I <sub>D</sub>	83	А
Q <sub>G</sub>	129	nC



### **Package Marking and Ordering Information**

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJ80N065	SJ80N065	TO-220	Tube	\	/	1000 Pcs

### Table 1. Absolute Maximum Ratings (T<sub>C</sub>=25℃ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V <sub>DS</sub>	Drain-Source Voltage (V <sub>GS</sub> =0V)	80	V
V <sub>G</sub> s	Gate-Source Voltage (V <sub>DS</sub> =0V)	±20	V
l <sub>a</sub>	Drain Current-Continuous(Tc=25°C)	83	Α
I <sub>D</sub>	Drain Current-Continuous(Tc=100℃)	53	А
I <sub>DM</sub> (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	332	Α
P <sub>D</sub>	Maximum Power Dissipation(Tc=25°C)	147	W
PD	Maximum Power Dissipation(Tc=100°C)	59	W
Eas	Avalanche energy (Note 2)	361	mJ
TJ, TSTG	Operating Junction and Storage Temperature Range	-55 To 150	С

### **Table 2. Thermal Characteristic**

Symbol	Parameter	Тур	Max	Unit
$R_{ heta JC}$	Thermal Resistance, Junction-to-Case		0.85	°C/W



Table 3. Electrical Characteristics ( $T_J=25^{\circ}C$  unless otherwise noted)

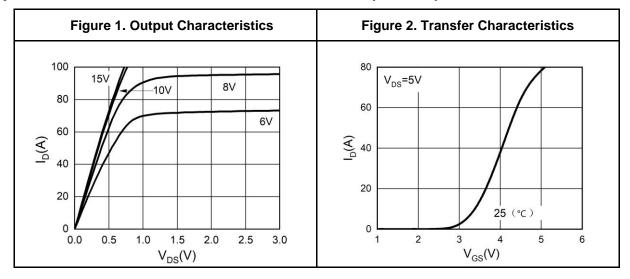
Symbol	Parameter	Conditions	Min	Тур	Max	
On/Off State	es					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	80			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =82V, V <sub>GS</sub> =0V			1	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V			±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250µA	2		4	V
<b>G</b> FS	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =20A		39.6		S
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =40A		6.8	9	mΩ
Dynamic Cl	naracteristics					
Ciss	Input Capacitance			7036		pF
Coss	Output Capacitance	V <sub>DS</sub> =25V,V <sub>GS</sub> =0V, f=1.0MHz		240		pF
Crss	Reverse Transfer Capacitance			214		pF
Rg	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1.0MHz		0.7		Ω
Switching F	Parameters		-	•		•
t <sub>d(on)</sub>	Turn-on Delay Time			22.4		nS
tr	Turn-on Rise Time	V <sub>GS</sub> =10V, V <sub>DS</sub> =40V, R <sub>L</sub> =1Ω, R <sub>GEN</sub> =3Ω		26.4		nS
t <sub>d(off)</sub>	Turn-Off Delay Time	RL-112, RGEN-312		99.6		nS
t <sub>f</sub>	Turn-Off Fall Time			11.6		nS
Qg	Total Gate Charge			129		nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> =10V, V <sub>DS</sub> =40V, I <sub>D</sub> =40A		22.4		nC
$Q_{gd}$	Gate-Drain Charge			32.8		nC
Source-Dra	in Diode Characteristics	•	•	•		
I <sub>SD</sub>	Source-Drain Current (Body Diode)				83	А
V <sub>SD</sub>	Forward on Voltage (Note 3)	V <sub>GS</sub> =0V, I <sub>S</sub> =40A			1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =20A, dI/dt=500A/μs		32		ns
Qrr	Reverse Recovery Charge	I <sub>F</sub> =20A, dI/dt=500A/μs		56		nC

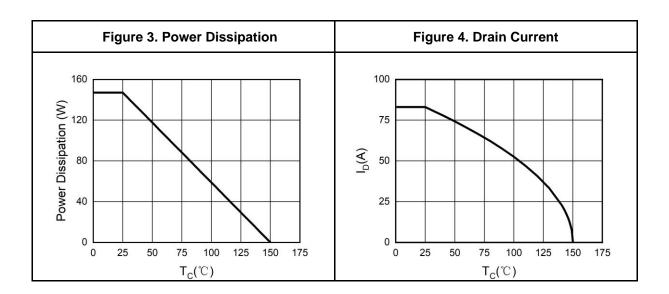
Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature. Notes 2.E<sub>AS</sub> condition:  $T_J$ =25 °C, $V_{DD}$ =10V, $V_G$ =10V, Rg=25 $\Omega$ , L=0.5mH.

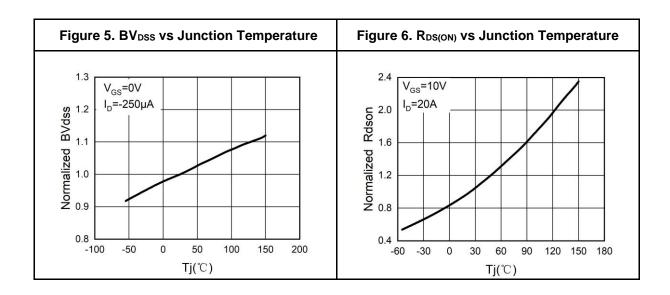
Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.



### **Typical Electrical And Thermal Characteristics (Curves)**

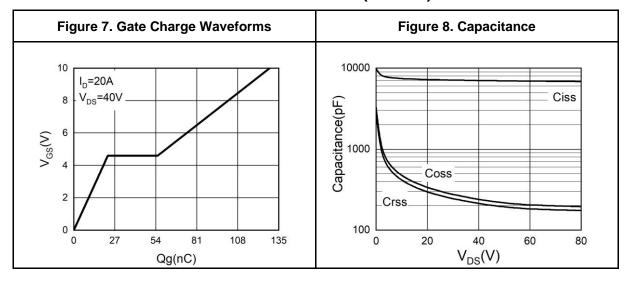


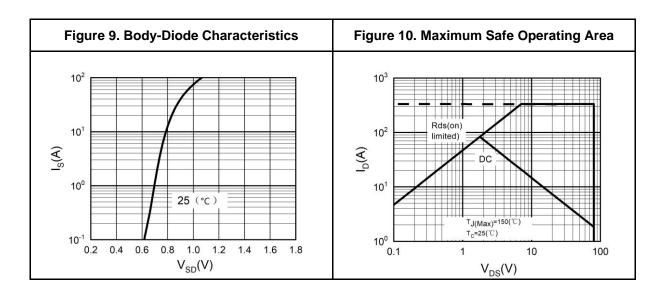




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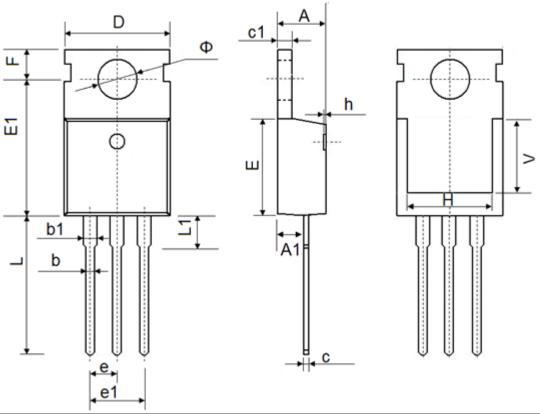
## **Typical Electrical And Thermal Characteristics (Curves)**







# **TO-220 Package Information**



Symbol	Dimens	sions In Millimeters	Dim	ensions In Inches
Symbol	Min.	Max.	Min.	Max
А	4.300	4.700	0.169	0.185
A1	2.200	2.600	0.087	0.102
b	0.700	0.950	0.028	0.037
b1	1.170	1.410	0.046	0.056
С	0.450	0.650	0.018	0.026
c1	1.200	1.400	0.047	0.055
D	9.600	10.400	0.378	0.409
E	8.8500	9.750	0.348	0.384
E1	12.650	12.950	0.498	0.510
е	2.540 TYP.		0.100TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
Н	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.750	14.300	0.502	0.563
L1	2.850	3.950	0.112	0.156
V	7.500	REF.	0.295 REF.	
Ф	3.400	4.000	0.134	0.157

#### Attention

This product described in this document can not be used in life support devices or systems, aircraft's control systems, and other applications whose failure can be reasonably expected to result in serious physical and/or material damage, apart from that when an application agreement is signed between customer and Wuxi Shangjia Semiconductor.

The performances and characteristics of this product in the independent testing state are displayed in this document. Wuxi Shangjia Semiconductor can't guarantee of the performances and characteristics of this described product that mounted in the customer's products or equipments as same as that in the independent testing state. So the customer should evaluate and test devices mounted in the customer's products or equipments.

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